

## **CLAIM AMENDMENTS:**

Claim 1 (Currently Amended): A surface laminar circuit board, comprising:  
an insulating layer;  
a conductive layer disposed on an upper surface of said insulating layer, said conductive layer having a hole formed therein;  
a photosensitive dielectric layer disposed on an upper surface of the conductive layer; and  
a conductive pad having over 50% thereof within an area defined by an outer periphery of the hole, said conductive pad being for receiving a surface mounted component thereon, said conductive pad being disposed within the hole, and being in direct contact with said insulating layer.

Claim 2 (Cancelled).

Claim 3 (Currently Amended): The surface laminar circuit board of claim 1 2, wherein said photosensitive dielectric layer is in direct contact with said the insulating layer by way of the hole, ~~and wherein said conductive pad is disposed directly on an upper surface of said photosensitive dielectric layer, said dielectric layer separating said conductive pad from said conductive layer and from said insulating layer.~~

Claim 4 (Cancelled).

Claim 5 (Original): The surface laminar circuit board of claim 1, wherein said insulating layer is an FR4 insulating layer.

Claim 6 (Previously Presented): The surface laminar circuit board of claim 1, wherein said conductive layer comprises a ground layer.

Claim 7 (Previously Presented): The surface laminar circuit board of claim 6, wherein said ground layer is comprised of copper.

Claim 8 (Original): The surface laminar circuit board of claim 1, wherein said hole is formed by etching.

Claim 9 (Currently Amended): The surface laminar circuit board of claim 1 2, wherein said photosensitive dielectric layer has a thickness, in a region over said ~~the~~ conductive layer, less than about 50 micrometers.

Claim 10 (Currently Amended): The surface laminar circuit board of claim 1 2, wherein said photosensitive dielectric layer has a thickness, in a region over said ~~the~~ conductive layer, equal to or less than about 40 micrometers.

Claim 11 (Currently Amended): The surface laminar circuit board of claim 1 2, further comprising signal traces disposed directly on said photosensitive dielectric layer.

Claim 12 (Original): The surface laminar circuit board of claim 1, wherein said conductive pad is disposed completely within the area defined by the outer periphery of the hole.

Claims 13-20 (Cancelled).

Claim 20 (Currently Amended): A surface laminar circuit board, comprising:  
an insulating layer;

a ground conductive layer disposed on an upper surface of said insulating layer, said conductive layer having a hole formed therein;

a photosensitive dielectric layer disposed on an upper surface of said ~~the~~ ground conductive layer, said dielectric layer having a photo micro-via formed therein;

a signal trace disposed on said photosensitive dielectric layer, and being electrically coupled with said ground conductive layer by way of said photo micro-via;

a conductive pad having over 50% thereof within an area defined by an outer periphery of the hole, and being electrically coupled with said signal trace, said conductive pad being disposed within the hole, and being in direct contact with said insulating layer; and

a surface mounted component mounted on said conductive pad.

Claim 21 (Currently Amended): The surface laminar circuit board of claim 20, wherein said photosensitive dielectric layer is in direct contact with said ~~the~~ insulating layer by way of the hole, ~~and wherein said conductive pad is disposed directly on an~~

~~upper surface of said photosensitive dielectric layer, said dielectric layer separating said conductive pad from said conductive layer and from said insulating layer.~~

Claim 22 (Cancelled).

Claim 23 (Currently Amended): A surface laminar circuit board, comprising:

an insulating layer;

a sheet of conductive material disposed on an upper surface of said insulating layer, said sheet of conductive material having a hole formed therein, the hole exposing an upper surface ~~a portion~~ of said insulating layer, the said sheet of conductive material ~~completely~~ surrounding an area defined by the hole, the area being in registration with, and corresponding in shape and size, to the upper surface ~~portion~~ of said insulating layer exposed by the hole;

a dielectric layer disposed on an upper surface of said conductive material and completely filling the hole so as to cover the upper surface of said insulating layer exposed by the hole; and

a conductive pad having a major portion thereof disposed directly over the ~~portion of said insulating layer exposed by the hole, and being completely disposed~~ directly on said dielectric layer, said conductive pad being for receiving a surface mounted component thereon.

Claim 24 (Currently Amended): The surface laminar circuit board of claim 23, wherein said dielectric layer is in direct contact with the upper surface ~~portion~~ of said

insulating layer exposed by the hole, and wherein said ~~conductive pad is disposed in direct contact with an upper surface of said dielectric layer,~~ said dielectric layer separates separating said conductive pad from said conductive material and from said insulating layer.

Claim 25 (Previously Presented): The surface laminar circuit board of claim 23, wherein said conductive material comprises a ground layer.

Claim 26 (Previously Presented): The surface laminar circuit board of claim 25, wherein said dielectric layer has a thickness, in a region over said conductive material, less than about 50 micrometers.

Claim 27 (Previously Presented): The surface laminar circuit board of claim 25, wherein said dielectric layer has a thickness, in a region over said conductive material, equal to or less than about 40 micrometers.

Claim 28 (Currently Amended): The surface laminar circuit board of claim 25, wherein all of said conductive pad is disposed over the upper surface ~~portion~~ of said insulating layer exposed by the hole.

Claim 29 (Currently Amended): The surface laminar circuit board of claim 23, wherein all of said conductive pad is disposed over the upper surface ~~portion~~ of said insulating layer exposed by the hole.